Panasonic

Zener Diode

DZ2730000L Silicon epitaxial planar type

For constant voltage / For surge absorption circuit DZ2S300 in SSSMini2 type package

Features

- · Excellent rising characteristics of zener current Iz
- Low zener operating resistance Rz
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)
- Marking Symbol: GG

Packaging

Embossed type (Thermo-compression sealing) 10 000 pcs / reel (standard)

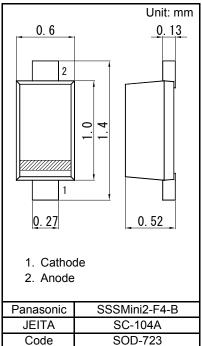
■ Absolute Maximum Ratings Ta = 25 °C

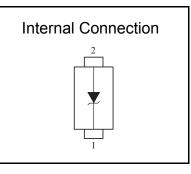
Parameter	Symbol	Rating	Unit
Repetitive peak forward current	IFRM	200	mA
Total power dissipation ^{*1}	PT	120	mW
Electrostatic discharge *2	ESD	±8	kV
Junction temperature	Tj	150	°C
Operating ambient temperature	Topr	-40 to +85	°C
Storage temperature	Tstg	-55 to +150	°C

 Storage temperature
 Tstg
 -55 to
 +150
 °(

 Note)
 *1: Mounted on glass epoxy print board. (45 mm x 45 mm x 1 mm) Solder in (0.4 mm x 0.3 mm)

*2: Test method:IEC61000_4_2(C = 150 pF,R = 330 Ω, Contact discharge:10 times)





	Electrical Characteristics Ta = 25 °C					
_	Parameter	Symbol	Conditions	Min	Тур	Max
	Forward voltage	VF	IF = 10 mA			1.0
	Zener voltage *1, *2	VZ	IZ = 2 mA	28.50		31.50
	Zener operating resistance	RZ	IZ = 2 mA			160
	Zener rise operating resistance	RZK	IZ = 0.5 mA			160

IR

 Temperature coefficient of zener voltage *3
 SZ
 IZ = 2 mA
 28.7
 mV/°C

 Note)
 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.

VR = 23 V

2. Absolute frequency of input and output is 5 MHz.

3. *1 The temperature must be controlled 25 °C for VZ mesurement.

VZ value measured at other temperature must be adjusted to VZ (25 °C)

*2 VZ guaranted 20 ms after current flow.

*3 Tj = 25 °C to 150 °C

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Unit

V

v

Ω

Ω

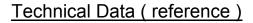
μA

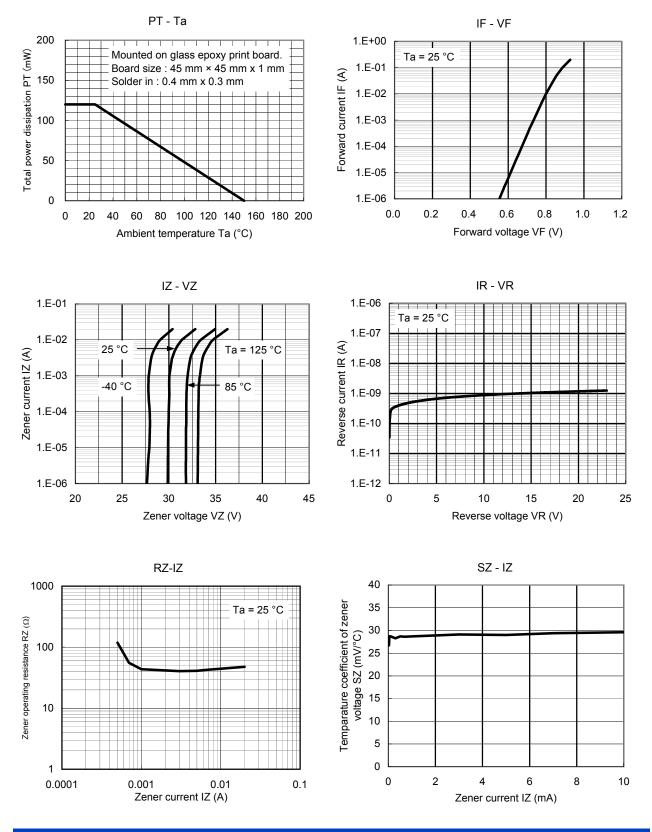
0.05

Reverse current



Zener Diode DZ2730000L







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Technical Data (reference) Rth - t Ct - VR 16 1000 (1) Ta = 25 °C 14 Terminal capacitance Ct (pF) Rth(j-l) = 100 °C/W Thermal resistance Rth (°C/W) f = 1 MHz (2 12 100 10 8 6 10 (1) Non-heat sink 4 (2) Mounted on glass epoxy print board. Board size : 45 mm × 45 mm x 1 mm 2 Solder in : 0.4 mm x 0.3 mm 0 1 11111 0 5 10 15 20 25 0.001 0.01 0.1 1 10 100 1000 Reverse voltage VR (V) Time t (s) PZSM - tw 100 Ta = 25 °C Non-repetitive reverse surge power dissipation PZSM (W) 10 1 0.1 100 1000 10000

Pulse width tw (µs)

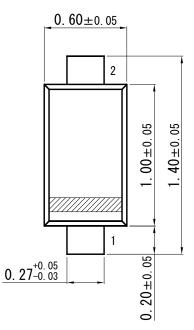
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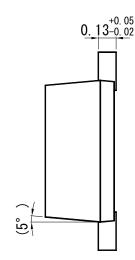


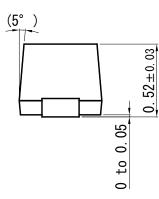
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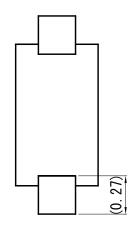
Unit: mm

SSSMini2-F4-B

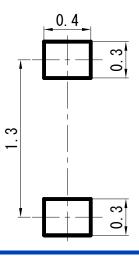








Land Pattern (Reference) (Unit: mm)



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